

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	B00
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	267		2	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		3	
		18	L2		
B-RaS-FR4-DS-1.194mm-018+018-TG150-HF...	50203144	1158		4	
		18	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	216		5	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		6	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		7	
		18	L4		
B-RaS-FR4-DS-1.194mm-018+018-TG150-HF...	50203144	1158		8	
		18	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	267		9	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		10	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	11	

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

3174 µm

Version 1.2.20.35

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